

4-1-53

PATENT APPLICATION  
Docket No. 11675.184.1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Salman Akram

Serial No. 107033,233

Filed: December 28, 2001

For: **CHIP PACKAGE WITH GREASE HEAT SINK  
AND METHOD OF MAKING**

Confirmation No.: 9685

Examiner: Khiem D. Nguyen

)  
)  
)  
) Art Unit  
) 2823

RECEIVED  
MAY 26 1970  
TELETYPE UNIT

## AMENDMENT AND RESPONSE

Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action mailed from the United States Patent and Trademark Office on December 31, 2002, please enter the following amendments and remarks into the file of the above-identified application.